ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES® International and Pa	IPC. Bannockł	ourn. Illinois. A	Il rights reserved un ntions.	nder both	This docume level parts, t	ent is a declaration en	n of the substat compasses all l	nces within the manufactor lower level materials for v	urer listed which the	item. Note: if manufacturer	the item is an as has engineering	sembly with low responsibility.	
				Form Type ³ Distribute	 Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information 					on			
Supplier Information													
Company name* Company			npany unique ID			Unique ID Authority				Response Date*			
nsemi									2024-05-10				
tontact Name Title - Contact					Phone - Contact*				Email - Contact*				
Product-Env-Stewards Product Enviro Comp			ro Compliance	Compliance		NA			Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Representative			sentative	Phone - Representative*			ntative*	Email		nail - Representative*			
Product-Env-Stewards Product Enviro Co			o Compliance		NA			Produ	Product-Env-Stewards@onsemi.com				
Requester Item Number	Requester Item Number Mfr Item Nur		Number Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	CS8361	CS8361YDPSR7G ANA 5V DUAL L		DO REG		2024-05-10	MY1			1421.5	mg	Each	
Ianufacturing Proccess Inform	ation												
Terminal Plating / Grid Array M	Terminal Plating / Grid Array Material Terminal Base Alloy		Alloy J	-STD-020 MSL	Rating	Peak Proce	ss Body Tempe	erature Max Time at Pea	k Temper	ature Numbe	er of Reflow Cy	eles	
Matte Tin (Sn) - annealed CU Alloy 3				260	C	30	seco	onds 3					
omments													
ITENTION: MSL 3 Rated item requir	es Bake and D	ry Pack (after	electrical test)										
or more information regarding materia	l composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in the spect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			ance category (JIG or Requester) or enter [F] Optionally enter the positive (+) ar				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.19	mg	Supplier	Silicon (Si)	7440-21-3		0.19	mg
Die Attach	11.34	mg	А	Lead (Pb)	7439-92-1	7a	10.773	mg
			Supplier	Tin (Sn)	7440-31-5		0.567	mg
Lead Frame	851.91	mg	В	Nickel (Ni)	7440-02-0		2.5557	mg
			Supplier	Copper (Cu)	7440-50-8		849.3542	mg
Mold Compound-Black	529.31	mg		Epoxy Phenol Resin	proprietary data		55.5775	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		473.7325	mg
Plating	27.15	mg	Supplier	Tin (Sn)	7440-31-5		27.15	mg
Wire Bond - Au	1.6	mg	Supplier	Gold (Au)	7440-57-5		1.6	mg